

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Kenji MORIMOTO et al.

Serial No.: New Application

Filed: March 20, 2002

For: FLIP CHIP PACKAGE, CIRCUIT BOARD THEREOF AND
PACKAGING METHOD THEREOF

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the above-identified application,
please enter the following specification changes as noted
below:

IN THE CLAIMS:

Please amend claims 3 and 4 as follows:

3. (Amended) The flip-chip packaging method according to
claim 1, wherein said electrode material film remaining after
development is trapezoidal in cross section that is wider as it
goes farther away from said circuit board.

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4. (Amended) The flip-chip packaging method according to claim 1, wherein said circuit electrode is arc-shaped in cross section.

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REMARKS

Claims 1-6, as amended, remain herein. Claims 3 and 4 have been amended hereby.

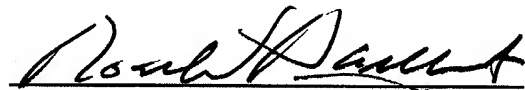
This Preliminary Amendment is submitted to eliminate multiply dependent claims from the above-identified application.

Examination of this application on its merits is respectfully requested.

Respectfully submitted,

PARKHURST & WENDEL, L.L.P.

March 20, 2002
Date


Roger W. Parkhurst
Registration No. 25,177

Attachment:

Mark Up of Amended Claims 3 and 4

RWP/ame

Attorney Docket No. YMOR:242

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